



Thermal evaporator



Description

Source material (in the form of pellets, shots) is placed in a vacuum chamber on resistance heated metal boats or ceramic crucible heated until its surface atoms have sufficient energy to leave the surface. At this point they will traverse the vacuum chamber, at thermal energy (less than 1 eV), and coat a substrate positioned above the evaporating material.

Specifications / Capabilities

Ultimate chamber pressure: 5×10^{-7} mbar.

Substrate sizes: up to 5"x5".

The substrate temperature can be controlled in range 40 -90° C with water chiller.

Standard Tolerance: 10-15%

Materials

Titanium. Maximum film thickness: 500 nm

Palladium. Maximum film thickness: 500 nm

Gold. Maximum film thickness: 2 μ

Link

<http://www.odemltd.com/>

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